

S/N 09/897,320

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: George Hsieh

Examiner: Gregory Thompson

Serial No.: 09/897,320

Group Art Unit: 2835

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Title: ELECTRONIC ASSEMBLY WITH SOLDERABLE HEAT SINK AND
METHODS OF MANUFACTUREFAX RECEIVED
DEC 11 2002

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SUPPLEMENTAL AMENDMENTCommissioner for Patents
Washington, D.C. 20231

Further in response to the Office Action mailed on June 17, 2002, please amend the above-identified patent application as follows:

IN THE CLAIMS

Please substitute the claim set in the appendix entitled "Clean Version of Pending Claims" for the previously pending claim set. The substitute claim set reflects the cancellation of claim 16, the amendment of claims 1-3, 12, 13, and 17, and the addition of new claims 31-41.

Please cancel claim 16.

Please amend claims 1-3, 12, 13, and 17 as indicated below. The specific amendments to individual claims are detailed in the following marked-up set of claims.

1. (Twice Amended) An electronic assembly comprising:

a substrate having at least one hole therein;

a heat sink having at least one mounting pin; and

at least one heat-producing component attached to the substrate, wherein the heat sink is disposed over the at least one heat-producing component and the substrate, wherein the heat-producing component is sandwiched between the substrate and the heat sink, wherein a thermal interface material is disposed between the heat sink and the heat-producing component to couple [bond] the heat sink to the heat-producing component, and wherein the at least one mounting pin of the heat sink is soldered into the at least one hole of [to] the substrate.